

Features

- Very small size of 1206
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency recognition: UL, CSA, TUV

SEL-TISE

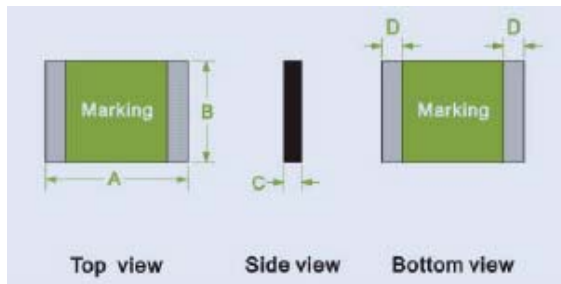


LP-NSM series

Surface-mount devices

Product Dimensions (mm)

Part number	A	B	C	D
	Max	Max	Max	Min
LP-NSM035	3.50	1.80	0.85	0.10
LP-NSM050	3.50	1.80	0.85	0.10
LP-NSM075	3.50	1.80	1.30	0.10
LP-NSM110	3.50	1.80	1.30	0.10
LP-NSM150	3.50	1.80	2.25	0.10



Marking System

W — Product family

W: LP-NSM035
 A: LP-NSM050
 Y: LP-NSM075
 O: LP-NSM110
 N: LP-NSM150

Electrical Characteristics

Part number	I_H	I_T	V_{max}	I_{max}	T_{trip}		R_{min}	R_{1max}
	(A)	(A)	(V)	(A)	Current(A)	Time(S)	()	()
LP-NSM035	0.35	0.75	6	40	8.0	0.10	0.30	1.20
LP-NSM050	0.50	1.00	6	40	8.0	0.10	0.15	0.70
LP-NSM075	0.75	1.50	6	40	8.0	0.20	0.10	0.29
LP-NSM110	1.10	1.80	6	40	8.0	3.00	0.055	0.21
LP-NSM150	1.50	3.00	6	40	8.0	1.00	0.04	0.12

I_H =Hold current: maximum current at which the device will not trip at 25 °C still air.

I_T =Trip current: minimum current at which the device will always trip at 25 °C still air.

V_{max} =Maximum voltage device can withstand without damage at rated current.

I_{max} =Maximum fault current device can withstand without damage at rated voltage.

T_{trip} =Maximum time to trip(s) at assigned current.

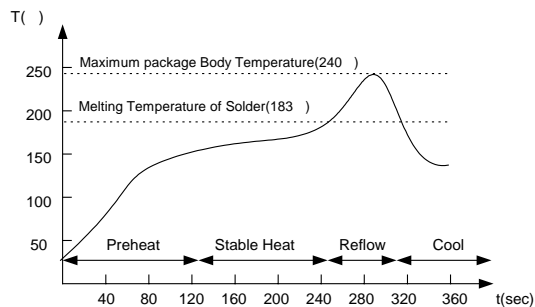
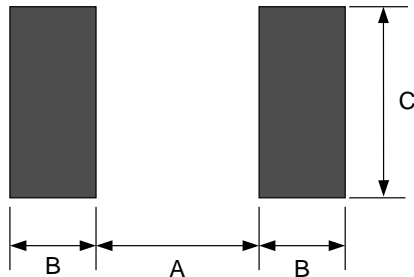
R_{min} =Minimum device resistance at 25 °C prior to tripping.

R_{1max} =Maximum device resistance measured in the nontripped state 1 hour post reflow.

Test Procedures And Requirements

Test	Test Conditions	Accept/Reject Criteria
Resistance	In still air @ 25	R_{min} R R_{max}
Time to Trip	Specified current, V_{max} , 25	T maximum Time to Trip
Hold Current	30min, at I_H	No trip
Trip Cycle Life	V_{max} , I_{max} , 100cycles	No arcing or burning
Trip Endurance	V_{max} , 24hours	No arcing or burning

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-NSM035	1.80	1.00	1.80
LP-NSM050	1.80	1.00	1.80
LP-NSM075	1.80	1.00	1.80
LP-NSM110	1.80	1.00	1.80
LP-NSM150	1.80	1.00	1.80

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape and Reel:

LP-NSM035~ LP-NSM050.....4000pcs per reel

LP-NSM075~ LP-NSM110.....3000pcs per reel

LP-NSM150.....2000pcs per reel